

Conference Program at a glance

Day 2 Tuesday June 8, 2021

in-adhesives

Symposium on Innovations in
Adhesives and their Applications

08:30 OPENING ZOOM PLATFORM AND IT-CHECK


09:00  Welcome by Chair: SVEN WIEMER; SCHILL + SEILACHER "STRUKTOL"

09:00  DR. MICHAEL A. KRAUS; M&M NETWORK-ING
Constitutive Modelling with Physics-informed Machine and Deep Learning - A Case Study with TSSA Adhesives

09:25 Q&A

09:30  DR. FRANK BURBULLA; Dr. Ing. h. c. F. PORSCHE AG
Modelling of Adhesively Bonded Joints in CAE-Models at Porsche – The Future Challenges

09:55 Q&A

10:00  DR. CLAUDIO DI FRATTA; SIKA SERVICES AG
New Adhesive Solutions for Designing and Bonding Composite Structures in Commercial Transportation


10:25 Q&A

10:30  NIKLAS GÜNTHER; TU BRAUNSCHWEIG / INSTITUTE OF JOINING AND WELDING
Consideration of Process-Related Adhesive Damage in Computational Structural Simulations

10:55 Q&A

11:00  OLIVIER DEFRAIN; TOTAL CRAY VALLEY
Resorcinol and Formaldehyde Free Coating Treatment Based on Functionalized Polybutadiene

11:25 Q&A

11:30  **KEYNOTE**
DR. RENÉ HENSEL; INM - LEIBNIZ INSTITUTE FOR NEW MATERIALS
Adhesives in Space – Opportunities and Challenges


Q&A

11:30 - 14:00 NETWORKING WITH AIRMEET

14:00  Welcome by Chair: DR. BELINDA BERNS; VISTEON ELECTRONICS GERMANY

14:00  DR. ARNO MAURER; OST - EASTERN SWITZERLAND UNIVERSITY OF APPLIED SCIENCE
Lifetime Assessment of Functional Polymers used in Electronic Packaging


14:25 Q&A

14:30  ANAS HALLAK; UNIVERSITY OF FREIBURG / IMTEK
Assessment of High-Temperature Reliability of Adhesion Promoter for Self-Healing Mechanisms in Thermoplastic, Media-Tight Injection Molded Housings

14:55 Q&A

15:00  JOWAT SE; DR. HARTMUT HENNEKEN
Novel Hotmelt Adhesives for Optimized Photovoltaics Wafer Production Processes

15:25 Q&A

15:30  HEINRICH LEICHT; SKZ-GERMAN PLASTICS CENTER
Enhancing the Electrical Conductivity of Flexible Adhesives Using Nanocarbons

15:55 Q&A